METHOD FOR PACKAGING AN OPTOELECTRONIC DEVICE AND PACKAGE FORMED THEREBY

ABSTRACT

A layer of clear encapsulant (115) is disposed and cured on the photosensitive portion (110) of an optoelectronic die (105). The encapsulant (115) provides a protective cover over the photosensitive portion (110) of the die (105). While the steps of disposing and curing the encapsulant (115), must necessarily be done in a Class 100 clean room, subsequent packaging steps can advantageously be performed without the need for a Class 100 clean room. In addition, the semiconductor optoelectronic die (105) with the encapsulant (115) can be flip chip mounted onto a substrate (135) to form a flip chip semiconductor optoelectronic package (100). Alternatively, the semiconductor die with the encapsulant (115) can be wire bonded to leads on a substrate to form a wire bonded semiconductor optoelectronic package.

FIG. 1 accompanies this abstract.